

Equipment List, Electrical

Applicable for F305

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1 General

This document describes the equipment needed, in addition to the equipment listed in the Mechanical Equipment List, to upgrade the applicable product's software, functional test and to repair the product at an Electrical Repair Level. The first section is equipment that can be purchased from a Sony Ericsson Parts and Tools warehouse. The second section is equipment that must be purchased from other vendors.

2 Column Definitions

Description Columns

- Description = The name of the equipment.
- Part Number = The Sony Ericsson part number to use when ordering from a Sony Ericsson Parts and Tools warehouse.
- Comments = Additional information that helps to specify or clarify the equipment.
- Picture

Process Columns


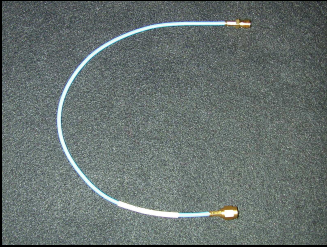
These columns show which processes use the equipment. An "X" in a column indicates that the equipment must be used, and a "Z" in a column indicates that the use of that equipment is optional.

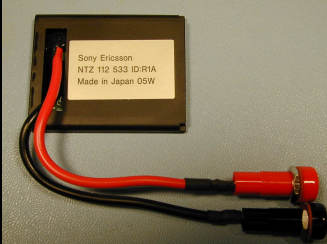
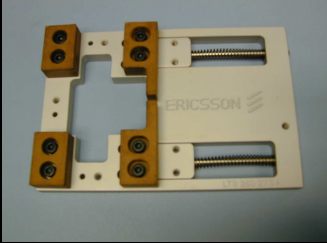

Customization:	Equipment necessary to perform a Customization/Activation.
Go/No Go test:	Equipment necessary for Go/No Go testing.
Repair:	Equipment necessary for replacing soldered components.



3 Repair Equipment

Some of the required equipment will be orderable from Sony Ericsson and some equipment has to be sourced locally. The following sections are structured based on whether equipment is obtained from Sony Ericsson or from a local supplier.

3.1 Repair Equipment orderable from Sony Ericsson

				Customization	Go/No Go Test	Repair
Description	Part Number	Comments	Picture			
RF Test Cable Flexible 1M	RPM 119 855				X	
RF Cable	RPM 119 891	The Short RF Cable is used to connect from the Shield box plate to the Phone.			Z	

				Customization	Go/No Go Test	Repair
Description	Part Number	Comments	Picture			
Dummy Battery	NTZ 112 533	If using the Battery Eliminator to power the handset during the GNG Test or Calibration routine, you must use a high quality DC source.		Z	Z	
Rework Fixture for PCB	LTD 260 273	Used to hold the PCB during repair.				X
RF Connector SMK	SXA1097057	Used with the RF Cable.			Z	

				Customization	Go/No Go Test	Repair
Description	Part Number	Comments	Picture			
USB Activation Dongle	NTZ 112 1071	Used for Activation in EMMA III NOTE: cannot be ordered via the standard ordering process, To order contact your Regional Representative		X		
DCU-65/USB Cable	RPM 131 12	This cable is needed for loading ITP software and customization/activation.		X		

3.2 Repair Equipment that should be obtained from local Suppliers

		Customization	Go/No Go Test	Repair
Description	Comments			
<p>RF Shield Package</p> <p>Rohde&Schwarz RF Shield Package</p> <ul style="list-style-type: none"> CMU-Z10 – Antenna Coupler (Partnr: 1150.0801.10) CMU-Z11 – RF Shield Cover (Partnr. 1150.1008.02) 	<p>Using an RF shield package is one of the options for testing the applicable product(s). Testing of the applicable product(s) can also be performed by using the combination of an RF Probe and an RF cable.</p> <p><i>Spare parts for mobile phone fixation for R&S CMU-Z10 are available for purchase from Rohde&Schwarz:</i></p> <ul style="list-style-type: none"> Grid Positioning Plate – 1158.9789.00 L-shaped bracket – 1158.9808.00 Stabilizing pieces – 1158.9820.00 <p>NOTE: The Rohde & Schwarz package will require the use of a precision N-type male to SMA female RF adapter to mate with the SEMC RF cable.</p> <p>NOTE: If you are using a different RF Shield Package than Rohde & Schwartz, special attenuation factors for Go/No-Go test are required.</p>		Z	

		Customization	Go/No Go Test	Repair
Description	Comments			
RF adapter for RF shield box <ul style="list-style-type: none"> The adapter for a Rohde & Schwarz Shield box must be a precision N-type male to SMA female adapter. 	This adapter is used to connect the RF shield box to the RF cable and is only required if a shield package is going to be used for testing. Recommended source: <ul style="list-style-type: none"> Pasternack Enterprises – (949) 261-1920 or www.pasternack.com Part number: PE9430		Z	

		Customization	Go/No Go Test	Repair
Description	Comments			
Willtek 4403/4405 Required Components: <ul style="list-style-type: none"> • 440x (4403 or 4405) • Option 4460 GSM/GPRS/EDGE HW • Option 4457 GSM Call Mode • Option 4458 GSM Non-Call Mode • Option 4468 EDGE Call Mode • Option 4449 EDGE Non-Call Mode • Option 4475 ACPM for 440x • Option 4479 Baseband processing HW • Option 4466 WCDMA/UMTS Non-Call Mode • Option 4467 WCDMA/UMTS Call Mode • WMain 52 MHZ clock for 4400/3100 • Firmware Version 14.00 or higher 	Note: It is strongly recommended that the instrument vendor be contacted before ordering this setup to ensure that the options stated are still valid or that no part numbers have changed.		X	



		Customization	Go/No Go Test	Repair
Description	Comments			
Power Supply (w/digital readout) NOTE! <i>If using the Power Supply in conjunction with the Battery Eliminator (Dummy Battery) to power the phone during the GNG test or Calibration routine a high quality DC source that meets the following requirements <u>must</u> be used.</i>	Device Requirements: <ul style="list-style-type: none"> • Output Voltage: 0-5 volt minimum. • Output Current: 0-2 amps minimum. • Transient response time: < 100 μs Some examples of Power Supplies that meet these requirements are as follows: <ul style="list-style-type: none"> • Agilent 66xx ser • Agilent 663x series 	Z	Z	
Small Convection (Hot Air) Device	Device Requirements: <ul style="list-style-type: none"> • The device should allow variable adjustment over a temperature range. • The device should be capable of reaching an upper temperature of 426.7°C (800°F) or more. The range of airflow the device is capable of generating should fall under 20 litre/minute.			X

		Customization	Go/No Go Test	Repair
Description	Comments			
Large Convection (Hot Air) Device	<p>Use this device for large parts, shield cans, and BGA-type components.</p> <ul style="list-style-type: none"> The device should allow variable temperature adjustment and be capable of reaching an upper temperature of 426.7°C (800°F) or more. <p>The range of airflow the device is capable of generating should be above 20 litre/minute.</p>			X
Nozzles for Large Convection (Hot Air) Device	NOTE: Only necessary if you have a large convection device.			X
Temperature Probes (Thermocouples)	Used to measure temperatures on the board when replacing parts with the Large Convection Device or creating temperature profiles.			X
Digital Multi-meter	Used for troubleshooting failures.			Z
Microscope	Minimum magnification required is 10x.			X
GPIB Card	<p>National Instruments or Keithley</p> <p>NOTES:</p> <ul style="list-style-type: none"> Drivers are required and should be supplied with a card. 		X	
GPIB Cable	This cable is only required if a GPIB card is used.		X	

		Customization	Go/No Go Test	Repair
Description	Comments			
Power cable – Red NOTE: Only necessary if using the Battery Eliminator (Dummy Battery).	Cable Requirements: <ul style="list-style-type: none"> • Minimum cross sectional area of conductor = 1.2mm² • Maximum length = 1.5 m • One end of cable must have a male banana-type connector to be able to interface with the battery eliminator. The other end of the cable needs whatever connection is necessary to connect to the power supply that you have.	Z	Z	
Power cable – Black NOTE: Only necessary if using the Battery Eliminator (Dummy Battery).	Cable Requirements: <ul style="list-style-type: none"> • Minimum cross sectional area of conductor = 1.2mm² • Maximum length = 1.5 m • One end of cable must have a male banana-type connector to be able to interface with the battery eliminator. The other end of the cable needs whatever connection is necessary to connect to the power supply that you have.	Z	Z	



		Customization	Go/No Go Test	Repair
Description	Comments			
Component baking oven	<p>Temperature requirements: 125°C +5°C/-0°C Required for drying moisture sensitive components.</p> <p>Below are links to several companies that sell convection ovens.</p> <p>http://www.cascadetek.com/forcedlist.php</p> <p>http://www.wisoven.com/lab1.htm</p> <p>http://www.shellab.com/products.html</p> <p>http://www.terrauniversal.com/products/tempcontrol/ovens/imperiaivmechcon.php</p> <p>http://www.labsynergy.com/products_laboratoryovens.asp?keyword=*laboratoryovens</p>			X
FLUX	<p>Lead-free solder does not require a special flux. The "No Clean" flux used with leaded products is acceptable.</p> <p>Although some manufacturers are developing fluxes specially made for use with lead-free solder (higher evaporation temperatures, less smoke, etc.), these are not required.</p>			X

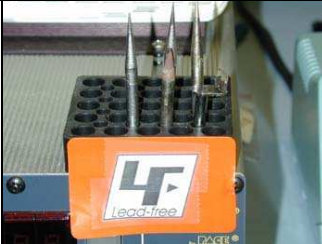


		Customization	Go/No Go Test	Repair
Description	Comments			
Low Static Heat Protection Tape	This tape is required to protect adjacent components from hot air.			X
Computer	<p>One of the following operating systems must be used:</p> <ul style="list-style-type: none"> Windows 2000 with service pack 2 or higher Windows XP <p>Minimum Requirements:</p> <ul style="list-style-type: none"> One unused PCI slot for GPIB card 2 USB Ports <p>The processor and RAM of the computer should at least meet the the minimum requirements specified by the operating system's manufacturer.</p>	X	X	
Test USIM	According to your Instrument supplier	X	X	
Printer	Optional, but recommended		Z	



		Customization	Go/No Go Test	Repair
Description	Comments			
Metal Cutters	<p>Use these to trim shield can fences when they obstruct access to parts.</p> <p>Cutters should be small enough to cut fences without damaging parts on the board.</p> <p>Cutters should be sharp enough to cut fences without twisting or pulling the fence.</p> <p>Recommended cutters available at www.MSCDirect.com:</p> <p>Knipex (left) - Mfr Part #: KN7803-5, MSC #: 32997462</p> <p>Xuron (right) - Mfr Part #: 2175AS, MSC #: 88356431</p>  			X

3.3 Lead-free Solder Equipment

The items in this table, and any other soldering tools or material that make physical contact with the solder, must remain lead-free. They must be adequately labelled to make their lead-free status clearly and easily recognized.

				Test	Repair
Pos	Description	Comments	Picture		
	Lead-free Solder Note: The solder must be composed of Tin, Silver, and Copper, and nothing else. The exact composition ratio may vary, but it must be Tin, Silver, and Copper only. This composition may also be known as SnAgCu or SAC.	Manufacturers of LF Solder: - Tamura (www.tamura-kaken.co.jp) Part # TLF-206-93F - Multicore (www.multicore.com) Part # 96SC - Senju (www.senju-m.co.jp) Part # M705			X
	Lead-free labels (sheet of 24) SEMC Part # SVF9301379 (These labels are available from the Sony Ericsson Parts and Tools Warehouse.)	Required for labeling all soldering tools and materials that contact the solder.			X

				Test	Repair
Pos	Description	Comments	Picture		
	Soldering Tips				X
	Soldering Iron If one work bench is divided to accommodate both leaded and lead-free solder, then each side of the bench should have its own iron.	<ul style="list-style-type: none"> The device should allow variable temperature adjustment and be capable of reaching an upper temperature of 426.7oC (800oF) or more. 			X
	Wicking Tape				X

				Test	Repair
Pos	Description	Comments	Picture		
	Tip Tinner				Z
	Tip Cleaner (steel wool)				Z

4 Revision History

Rev.	Date	Changes / Comments
1	2008-10-10	Initial release
2	2008-11-04	SERP Calibration sections updated
3	2009-07-22	Remove USB Computer Cable and column Calibration with SERP.